LQB18 Series  Reference Specification

1. Scope
This reference specification applies to LQB18N series, Chip Coil.

2. Part Numbering
(ex.)   LQ  B  18  N  N  R  22  N  0  D
(1)Product ID (2)Type (3)Dimension(L×W) (4)Category (5)Applications and Characteristics
(6)Inductance (7)Tolerance (8)Features (9)Electrode (10)Packaging (D:Taping / *B:Bulk)

*Bulk packing also available.

3. Rating

<table>
<thead>
<tr>
<th>Customer Part Number</th>
<th>MURATA Part Number</th>
<th>Inductance (nH)</th>
<th>Q (min.)</th>
<th>Self Resonant Frequency (MHz min.)</th>
<th>Rated Current (mA)</th>
<th>DC Resistance (Ω max.)</th>
<th>Initial Values</th>
<th>Values After Testing</th>
</tr>
</thead>
<tbody>
<tr>
<td>LQB18NNR22J10D</td>
<td></td>
<td>220</td>
<td>J ±5%</td>
<td>25</td>
<td>450</td>
<td>0.37</td>
<td>0.47</td>
<td></td>
</tr>
<tr>
<td>LQB18NNR22K10D</td>
<td></td>
<td></td>
<td>K ±10%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR22M10D</td>
<td></td>
<td></td>
<td>M ±20%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR22N10D</td>
<td></td>
<td></td>
<td>N ±30%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR27J10D</td>
<td></td>
<td>270</td>
<td>J ±5%</td>
<td></td>
<td>450</td>
<td>0.45</td>
<td>0.55</td>
<td></td>
</tr>
<tr>
<td>LQB18NNR27K10D</td>
<td></td>
<td></td>
<td>K ±10%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR27M10D</td>
<td></td>
<td></td>
<td>M ±20%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR27N10D</td>
<td></td>
<td></td>
<td>N ±30%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR33J10D</td>
<td></td>
<td>330</td>
<td>J ±5%</td>
<td>80</td>
<td>450</td>
<td>0.45</td>
<td>0.55</td>
<td></td>
</tr>
<tr>
<td>LQB18NNR33K10D</td>
<td></td>
<td></td>
<td>K ±10%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR33M10D</td>
<td></td>
<td></td>
<td>M ±20%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR33N10D</td>
<td></td>
<td></td>
<td>N ±30%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR39J10D</td>
<td></td>
<td>390</td>
<td>J ±5%</td>
<td></td>
<td>450</td>
<td>0.58</td>
<td>0.68</td>
<td></td>
</tr>
<tr>
<td>LQB18NNR39K10D</td>
<td></td>
<td></td>
<td>K ±10%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR39M10D</td>
<td></td>
<td></td>
<td>M ±20%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR39N10D</td>
<td></td>
<td></td>
<td>N ±30%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR47J10D</td>
<td></td>
<td>470</td>
<td>J ±5%</td>
<td></td>
<td>400</td>
<td>0.58</td>
<td>0.68</td>
<td></td>
</tr>
<tr>
<td>LQB18NNR47K10D</td>
<td></td>
<td></td>
<td>K ±10%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR47M10D</td>
<td></td>
<td></td>
<td>M ±20%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR47N10D</td>
<td></td>
<td></td>
<td>N ±30%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR56J10D</td>
<td></td>
<td>560</td>
<td>J ±5%</td>
<td></td>
<td>300</td>
<td>0.85</td>
<td>0.95</td>
<td></td>
</tr>
<tr>
<td>LQB18NNR56K10D</td>
<td></td>
<td></td>
<td>K ±10%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR56M10D</td>
<td></td>
<td></td>
<td>M ±20%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>LQB18NNR56N10D</td>
<td></td>
<td></td>
<td>N ±30%</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

- Operating Temperature : -55°C to +125°C
- Storage Temperature : -55°C to +125°C
4. Style and Dimensions

![Diagram of dimensions](image)

- Unit Mass (Typical value)
  - 0.005g

5. Marking

No marking.

6. Standard Testing Conditions

<table>
<thead>
<tr>
<th>Unless otherwise specified</th>
<th>In case of doubt</th>
</tr>
</thead>
<tbody>
<tr>
<td>Temperature: Ordinary Temp. (15°C to 35°C)</td>
<td>Temperature: 20°C ± 2°C</td>
</tr>
<tr>
<td>Humidity: Ordinary Humidity (25%(RH) to 85%(RH))</td>
<td>Humidity: 60%(RH) to 70%(RH)</td>
</tr>
<tr>
<td>Atmospheric pressure: 86kPa to 106kPa</td>
<td></td>
</tr>
</tbody>
</table>

7. Specifications

7-1. Electrical Performance

<table>
<thead>
<tr>
<th>No.</th>
<th>Item</th>
<th>Specification</th>
<th>Test Method</th>
</tr>
</thead>
<tbody>
<tr>
<td>7-1-1</td>
<td>Inductance</td>
<td>Meet item 3.</td>
<td>Measuring Frequency: 25MHz</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>Measuring Equipment: Agilent 4291A or the equivalent</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>Test Fixture: Agilent 16192A or the equivalent</td>
</tr>
<tr>
<td>7-1-2</td>
<td>Q</td>
<td></td>
<td></td>
</tr>
<tr>
<td>7-1-3</td>
<td>SRF</td>
<td></td>
<td></td>
</tr>
<tr>
<td>7-1-4</td>
<td>DC Resistance</td>
<td>Meet item 3.</td>
<td>Measuring Equipment: Digital multi meter</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>7-1-5</td>
<td>Rated Current</td>
<td>Self temperature rise shall be limited to 25°C max.</td>
<td>The rated current is applied.</td>
</tr>
</tbody>
</table>
### 7-2-1 Appearance and Dimensions
- **Specification**: Meet item 4.
- **Test Method**: Visual Inspection and measured with Slide Calipers.

### 7-2-2 Bonding Strength
- **Table 1**
- **Appearance**: No damage
- **DC Resistance**: Meet item 3.

### 7-2-3 Bending Strength
- **Substrate**: Glass-epoxy 100mm×40mm×1.6mm
- **Deflection**: 1.0mm
- **Speed of Applying Force**: 0.5mm/s
- **Keeping Time**: 30s

### 7-2-4 Vibration
- **Oscillation Frequency**: 10Hz to 55Hz to 10Hz for 1 min
- **Total Amplitude**: 1.5mm
- **Testing Time**: A period of 2 hours in each of 3 mutually perpendicular directions. (Total 6h)

### 7-2-5 Resistance to Soldering Heat
- **Pre-Heating**: 150°C±10°C, 60s~90s
- **Solder**: Sn-3.0Ag-0.5Cu
- **Solder Temperature**: 270°C±5°C
- **Immersion Time**: 10s±0.5s
- **Immersion and emersion rates**: 25mm/s
- **Then measured after exposure in the room condition for 48h±4h.**

### 7-2-6 Drop
- **Products shall be no failure after tested.**
- **Method**: free fall
- **Height**: 75cm
- **Attitude from which the product is dropped**: 3 direction
- **The number of times**: 3 times for each direction (Total 9 times)

### 7-2-7 Solderability
- **The electrodes shall be at least 95% covered with new solder coating.**
- **Flux**: Ethanol solution of rosin, 25(wt)%
- **Pre-Heating**: 150°C±10°C, 60s~90s
- **Solder**: Sn-3.0Ag-0.5Cu
- **Solder Temperature**: 240°C±5°C
- **Immersion Time**: 3s±1s
- **Immersion and emersion rates**: 25mm/s
7-3. Environmental Performance

It shall be soldered on the substrate.

<table>
<thead>
<tr>
<th>No.</th>
<th>Item</th>
<th>Specification</th>
<th>Test Method</th>
</tr>
</thead>
</table>
| 7-3-1 | Temperature Cycle   | Meet Table 1.                  | 1 cycle:  
1 step: -55°C (+0°C, -3°C) / 30min±3min  
2 step: Ordinary temp. / 10min to 15min  
3 step: +125°C (+3°C, -0°C) / 30min±3min  
4 step: Ordinary temp. / 10min to 15min  
Total of 100 cycles  
Then measured after exposure in the room condition for 48h±4h. |
| 7-3-2 | Humidity            | Temperature: 40°C±2°C          | Humidity: 90%(RH) to 95%(RH)  
Time: 1000h (+48h, -0h)  
Then measured after exposure in the room condition for 48h±4h. |
| 7-3-3 | Heat Life           | Temperature: 125°C±3°C         | Applying Current: Rated Current  
Time: 1000h (+48h, -0h)  
Then measured after exposure in the room condition for 48h±4h. |
| 7-3-4 | Cold Resistance     | Temperature: -55°C±2°C         | Time: 1000h (+48h, -0h)  
Then measured after exposure in the room condition for 48h±4h. |

8. Specification of Packaging

8-1. Appearance and Dimensions (8mm-wide paper tape 4mm-pitch)

1) Taping
   Products shall be packaged in the cavity of the base tape continuously and sealed by top tape and bottom tape.
2) Sprocket hole: The sprocket holes are to the right as the tape is pulled toward the user.
3) Spliced point: The base tape and top tape have no spliced point.
4) Cavity: There shall not be burr in the cavity.
5) Missing components number
   Missing components number within 0.1% of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

8-2. Tape Strength

1) Pull Strength
<table>
<thead>
<tr>
<th>Top tape</th>
<th>Bottom tape</th>
</tr>
</thead>
<tbody>
<tr>
<td>5N min.</td>
<td></td>
</tr>
</tbody>
</table>

2) Peeling off force of Top tape
   0.1N to 0.6N (Minimum value is typical.)
   *Speed of Peeling off: 300mm/ min
8-3. Taping Condition

(1) Standard quantity per reel: 4000pcs. / reel
(2) There shall be leader-tape (top tape and empty tape) and trailer-tape (empty tape) as follows.
(3) On paper tape, the top tape and the base tape shall not be adhered at the tip of the empty leader tape for more than 5 pitch.
(4) Marking for reel

The following items shall be marked on a label and the label is stuck on the reel.
(Customer part number, MURATA part number, Inspection number (+1), RoHS marking (+2), Quantity, etc)

*1) « Expression of Inspection No. »

(1) Factory Code
(2) Date
First digit : Year / Last digit of year
Second digit : Month / Jan. to Sep. → 1 to 9, Oct. to Dec. → O, N, D
Third, Fourth digit : Day

(3) Serial No.

*2) « Expression of RoHS marking »

(1) RoHS regulation conformity parts.
(2) MURATA classification number

(5) Outside package

These reels shall be packed in the corrugated cardboard package and the following items shall be marked on a label and the label is stuck on the box.
(Customer name, Purchasing order number, Customer part number, MURATA part number, RoHS marking (+2), Quantity, etc)

(6) Dimensions of reel and taping (leader-tape, trailer-tape)

8-4. Specification of Outer Case

<table>
<thead>
<tr>
<th>Outer Case Dimensions (mm)</th>
<th>Standard Reel Quantity in Outer Case (Reel)</th>
</tr>
</thead>
<tbody>
<tr>
<td>W</td>
<td>D</td>
</tr>
</tbody>
</table>

* Above Outer Case size is typical. It depends on a quantity of an order.
9. ⚠️ Caution

9-1. Limitation of Applications

Limitation of Applications
Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

1. Aircraft equipment
2. Aerospace equipment
3. Undersea equipment
4. Power plant control equipment
5. Medical equipment
6. Transportation equipment (vehicles, trains, ships, etc.)
7. Traffic signal equipment
8. Disaster prevention / crime prevention equipment
9. Data-processing equipment
10. Applications of similar complexity and/or reliability requirements to the applications listed in the above

10. Notice

This product is designed for solder mounting.
Please consult us in advance for applying other mounting method such as conductive adhesive.

10-1. Land pattern designing

- Standard land dimensions

10-2. Soldering Conditions

Products can be applied to reflow and flow soldering.

(1) Flux, Solder

<table>
<thead>
<tr>
<th>Flux</th>
<th>Use rosin-based flux, but not highly acidic flux (with chlorine content exceeding 0.2(wt)%). Do not use water-soluble flux.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Solder</td>
<td>Use Sn-3.0Ag-0.5Cu solder</td>
</tr>
<tr>
<td>Standard thickness of solder paste: 100 µm to 200 µm</td>
<td></td>
</tr>
</tbody>
</table>

(2) Soldering conditions

- Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.
- Insufficient pre-heating may cause cracks on the ferrite, resulting in the deterioration of product quality.
- Standard soldering profile and the limit soldering profile is as follows.
- The excessive limit soldering conditions may cause leaching of the electrode and/or resulting in the deterioration of product quality.

<table>
<thead>
<tr>
<th>Soldering</th>
<th>a</th>
<th>b</th>
<th>c</th>
</tr>
</thead>
<tbody>
<tr>
<td>Flow</td>
<td>0.7</td>
<td>2.2 to 2.6</td>
<td>0.7</td>
</tr>
<tr>
<td>Reflow</td>
<td>1.8 to 2.0</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

(in mm)
(3) soldering profile

- Flow soldering profile

- Reflow soldering profile

<table>
<thead>
<tr>
<th></th>
<th>Standard Profile</th>
<th>Limit Profile</th>
</tr>
</thead>
<tbody>
<tr>
<td>Pre-heating</td>
<td>150°C, 60s min.</td>
<td></td>
</tr>
<tr>
<td>Heating</td>
<td>250°C, 4s~6s</td>
<td>265°C ±3°C, 5s max.</td>
</tr>
<tr>
<td>Cycle of flow</td>
<td>2 times</td>
<td>2 times</td>
</tr>
</tbody>
</table>

10-3. Reworking with soldering iron

- Pre-heating: 150°C, 1 min
- Tip temperature: 350°C max.
- Soldering time: 3(+1, -0) seconds.
- Soldering iron output: 80W max.
- Tip diameter: ¥3mm max.
- Times: 2 times max.

Note: Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

10-4. Solder Volume

Solder shall be used not to be exceeded as shown below.

Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.
10-5. Attention regarding P.C.B. bending

The following shall be considered when designing and laying out P.C.B.’s.

(1) P.C.B. shall be designed so that products are not subject to the mechanical stress for board warpage.

*Products direction*

- **Poor example**
- **Good example**

Products shall be located in the sideways direction (Length: a-b) to the mechanical stress.

(2) Products location on P.C.B. separation.

Products (A, B, C, D) shall be located carefully so that products are not subject to the mechanical stress due to warping the board. Because they may be subjected the mechanical stress in order of A>C>B ≤ D.

10-6. Mounting density

Add special attention to radiating heat of products when mounting the inductor near the products with heating. The excessive heat by other products may cause deterioration at joint of this product with substrate.

10-7. Operating Environment

Do not use this product under the following environmental conditions, on deterioration of the Insulation Resistance of the Ferrite material and / or corrosion of Inner Electrode may result from the use.

- (1) in the corrodible atmosphere (acidic gases, alkaline gases, chlorine, sulfur gases, organic gases and etc.)
- (2) in the atmosphere where liquid such as organic solvent, may splash on the products.
- (3) in the atmosphere where the temperature / humidity changes rapidly and it is easy to dew.

10-8. Resin coating

The inductance value may change and/or it may affect on the product's performance due to high cure-stress of resin to be used for coating / molding products. So please pay your careful attention when you select resin. In prior to use, please make the reliability evaluation with the product mounted in your application set.

10-9. Cleaning Conditions

Products shall be cleaned on the following conditions.

- (1) Cleaning temperature shall be limited to 60°C max. (40°C max. for IPA.)
- (2) Ultrasonic cleaning shall comply with the following conditions, avoiding the resonance phenomenon at the mounted products and P.C.B.
  - Power: 20W// max. Frequency: 28kHz to 40kHz  Time: 5 min max.
- (3) Cleaner
  1. Alternative cleaner
    - Isopropyl alcohol (IPA)
  2. Aqueous agent
    - PINE ALPHA ST-100S
- (4) There shall be no residual flux and residual cleaner after cleaning.
  - In the case of using aqueous agent, products shall be dried completely after rinse with de-ionized water in order to remove the cleaner.
- (5) Other cleaning
  - Please contact us.

10-10. Handling of a substrate

After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate. Excessive mechanical stress may cause cracking in the product.
10-11. Storage Conditions

(1) Storage period
Use the products within 6 months after delivered.
Solderability should be checked if this period is exceeded.

(2) Storage conditions
- Products should be stored in the warehouse on the following conditions.
  Temperature : -10°C to 40°C
  Humidity : 15% to 85% relative humidity
  No rapid change on temperature and humidity
- Don’t keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
- Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be stored under the airtight packaged condition.

(3) Delivery
Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

11. Notes

(1) Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
(2) You are requested not to use our product deviating from the reference specifications.
(3) The contents of this reference specification are subject to change without advance notice.
   Please approve our product specifications or transact the approval sheet for product specifications before ordering.